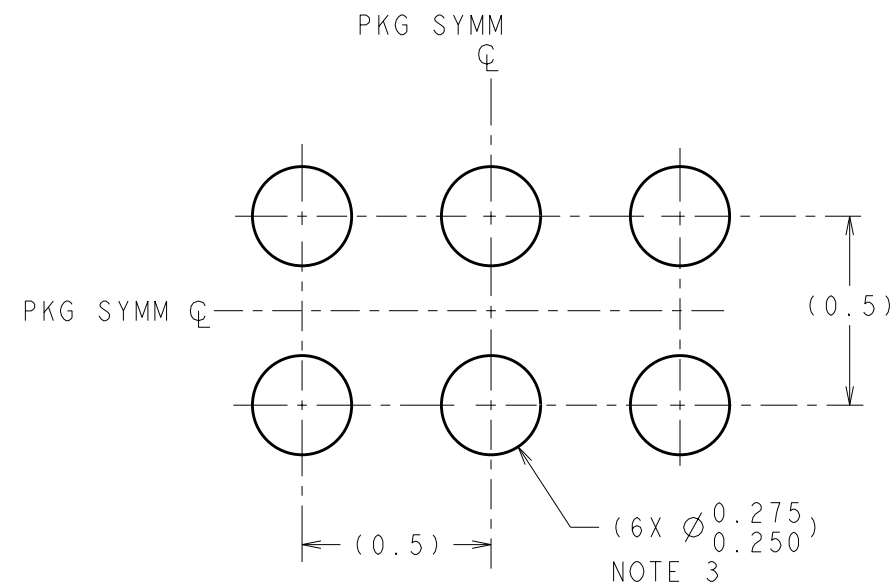
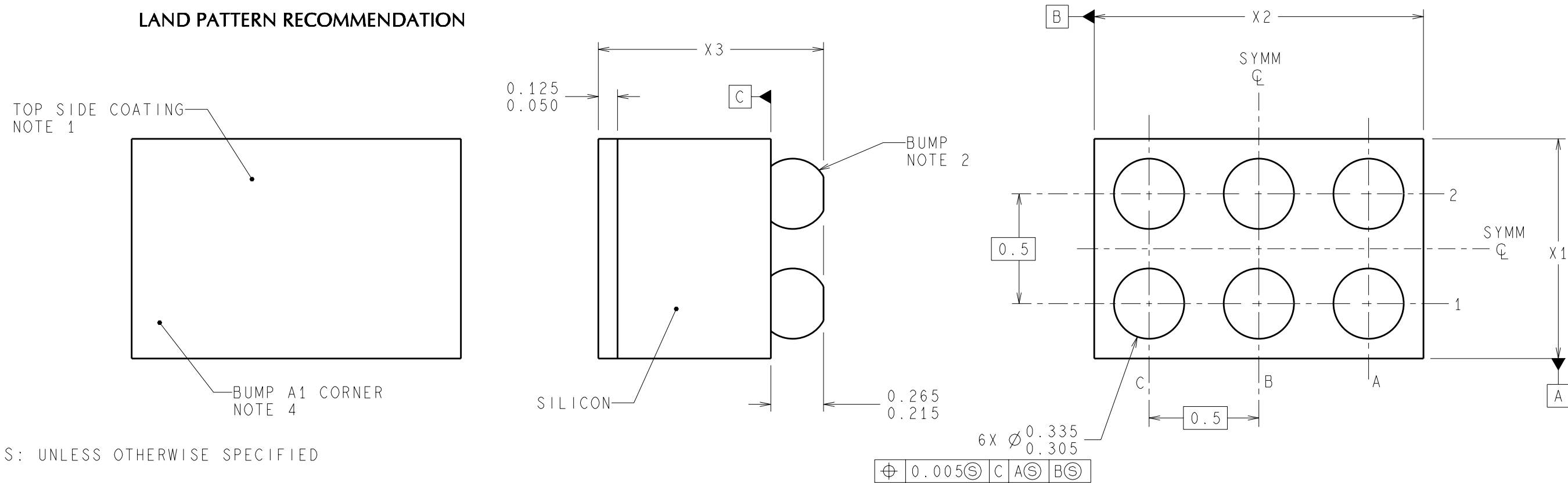


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	299	04/13/2001	MS/VP
B	CHANGE BUMPS NUMBERING ORDER PER JEDEC; JEDEC VARIATION WAS BC; UPDATE NOTE 4.	516	02/11/2002	MS/VP
C	BUMP HEIGHT DIM 0.265/0.215 WAS 0.235/0.205; ADD 'Z' 955 & '1' 980 TO COLUMN X1; ADD 'Z' 1463 & '1' 1488 TO COLUMN X2; REVISE NOTE 2; BUMP DIA 0.335/ 0.305 WAS 0.31/ 0.29; CHANGE DWG FORMAT TO B SIZE.	825	07/25/2003	MS/HN



DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY

LAND PATTERN RECOMMENDATION




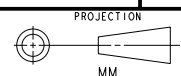
NOTES: UNLESS OTHERWISE SPECIFIED

- EPOXY COATING.
- FOR SOLDER BUMP COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- RECOMMEND NON-SOLDER MASK DEFINED LANDING PAD.
- PIN A1 IS ESTABLISHED BY LOWER LEFT CORNER WITH RESPECT TO TEXT ORIENTATION.
- XXX IN DRAWING NUMBER REPRESENTS PACKAGE SIZE VARIATION WHERE X1 IS PACKAGE WIDTH, X2 IS PACKAGE LENGTH AND X3 IS PACKAGE HEIGHT (SEE TABLE, SHEET 2).
EXAMPLE: BLA06AFA HAS WIDTH=1006, LENGTH=1641, HEIGHT=795
- REFERENCE JEDEC REGISTRATION MO-211, VARIATION BB.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	MARTA SUCHY	04/13/2001		
DFTG. CHK.	THANH LEQUANG	07/25/2003	MICRO SMD, 6 BUMP(LARGE), 0.5mm PITCH	
ENGR. CHK.	HAU NGUYEN	07/25/2003		
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
 MM	NTS	B	(SC)MKT-BLA06XXX	C
FORMERLY: N/A			SHEET 1 of 2	

REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
SEE SHEET 1				

PACKAGE DIMENSIONS					
X1 DESIGNATOR	X1 PACKAGE WIDTH $\pm 30 \mu\text{m}$	X2 DESIGNATOR	X2 PACKAGE LENGTH $\pm 30 \mu\text{m}$	X3 DESIGNATOR	X3 PACKAGE HEIGHT $\pm 100 \mu\text{m}$
Z	955	Z	1463	A	795
1	980	1	1488	B	945
A	1006	A	1514	C	995
B	1031	B	1539		
C	1057	C	1565		
D	1082	D	1590		
E	1107	E	1615		
F	1133	F	1641		
G	1158	G	1666		
H	1184	H	1692		
J	1209	J	1717		
K	1234	K	1742		
L	1260	L	1768		
M	1285	M	1793		
N	1311	N	1819		
P	1336	P	1844		
Q	1361	Q	1869		
R	1387	R	1895		
S	1412	S	1920		
T	1438	T	1946		
U	1463	U	1971		

APPROVALS		DATE	 2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DRAWN	MARTA SUCHY	04/13/2001				
DFTG. CHK.	THANH LEQUANG	07/25/2003				
ENGR. CHK.	HAU NGUYEN	07/25/2003				
 MM			SCALE	SIZE	DRAWING NUMBER	REV
			NTS	B	(SC)MKT-BLA06XXX	C
FORMERLY: N/A			SHEET 2 of 2			

**MICRO SMD, 6 BUMP(LARGE),
0.5mm PITCH**